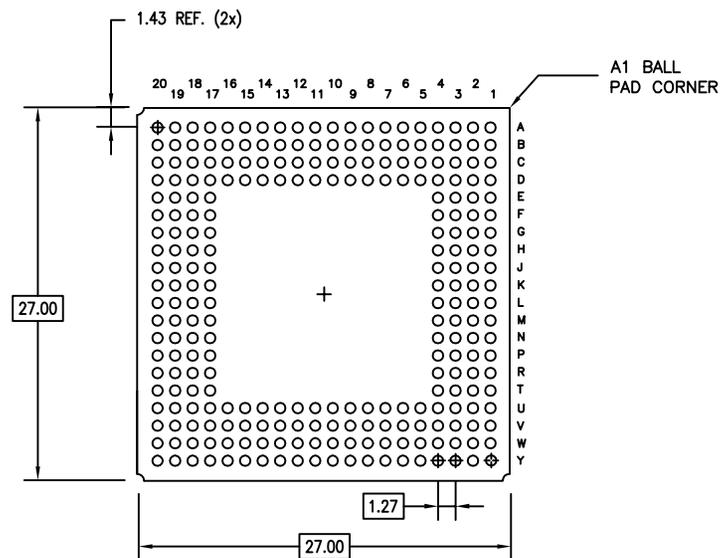
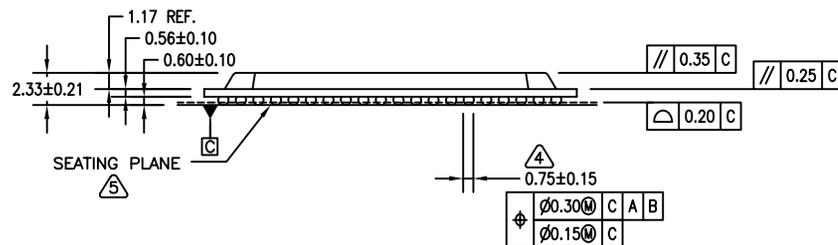


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.27 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM \square
5. PRIMARY DATUM \square AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO LEADED (-), LEAD FREE (+) PKG. CODES.
8. PACKAGE CODE: V256-2
V256-3
V256-5
V256-6

-DRAWING NOT TO SCALE-



TITLE:
PACKAGE OUTLINE, 256 BALLS PBGA,
27.0x27.0x2.33mm, 1.27mm PITCH, 4 LAYER

APPROVAL EDEN CHEN 10-20-10	DOCUMENT CONTROL NO. 21-0307	REV. B	1/1
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